



DATE	DRN
07/22/11	LKI

FOOTPRINT AS VIEWED FROM TOP OF SOCKET

<p>UNLESS OTHERWISE SPECIFIED</p> <p>DIMENSIONS APPLY AFTER PLATING</p> <p>INVENTOR CREATED FILE</p> <p>PROPRIETARY INFORMATION</p> <p>THIS DRAWING AND SUPPORTING CAD DATA IS PROPERTY OF PLASTRONICS SOCKET COMPANY</p>	<p>LINEAR DIMENSIONS</p> <p>.XX [XXX] = ±0.076 [0.003]</p> <p>X [XX] = ±0.25 [0.01]</p>	<p>DRN</p> <p>LKI</p> <p>CHK</p> <p>6/1/2010</p>	<p>PLASTRONICS</p> <p>2601 Texas Drive</p> <p>Irving, TX 75062</p>		
	<p>FEATURES: A</p> <p>= H-PIN CONTACT (H038LL1A)</p> <p>= COMPRESSION MOUNT</p>	<p>ENGR</p> <p>MFG</p>		<p>TITLE</p> <p>QFN HPIN SOCKET, 3x3mm, 0.50mm PITCH, 16+1 HPIN CONTACTS, COMPRESSION MOUNT</p>	
	<p>INTERPRET THIS DRAWING USING ASME Y14.5M-1994</p>	<p>UNITS</p> <p>SCALE</p> <p>NONE</p>		<p>mm [inch]</p> <p>SIZE</p> <p>B</p>	<p>SOCKET PART NO</p> <p>16QH50A13030</p>
				<p>DWG NO</p> <p>S16QH50A13030</p>	<p>SHEET 1 OF 1</p>

- NOTES:**
1. SUGGESTED PAD PLATING: 30µin HARD Au OVER 300µin Ni OVER 1oz Cu.
 2. ALL Au PADS SHOULD BE SAME HEIGHT.

THIS DRAWING IS SUBJECT TO CHANGE WITHOUT NOTICE. PLEASE REQUEST A CURRENT DRAWING WHEN LAYING OUT BOARDS.

